

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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500 mA, 30 V Schottky Barrier Diode

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current that offers the most optimal power dissipation in applications. They are housed in spacing saving micro-packaging ideal for space constraint applications.

Features

- Low Forward Voltage Drop 370 mV (Typ.) @ $I_F = 500 \text{ mA}$
- Low Reverse Current 52 μ A (Typ.) @ $V_R = 30 \text{ V}$
- 500 mA of Continuous Forward Current
- High Switching Speed
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|------------------|-------|------|
| Reverse Voltage | V _R | 30 | V |
| Forward Current (DC) | ΙF | 500 | mA |
| Forward Surge Current (60 Hz @ 1 cycle) | I _{FSM} | 3.0 | А |
| Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%) | I _{FRM} | 1.5 | А |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



ON Semiconductor®

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YL = Specific Device Code M Date Code



ORDERING INFORMATION

| Device | Package | Shipping† |
|----------------|----------------------|-----------------------|
| NSR05T30XV2T5G | SOD-523 (Pb-Free) | 8000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Min | Тур | Max | Unit |
|---|------------------------------------|-----|-------------|------------|------------|
| Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T _A = 25°C | R _{θJA} P _D | | | 489 250 | °C/W mW |
| Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T _A = 25°C | | | | 358 350 | °C/W mW |
| Junction and Storage Temperature Range | T _J , T _{stg} | | -55 to +150 | | °C |

- 1. Mounted onto a 4 in square FR-4 board 50 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
- 2. Mounted onto a 4 in square FR-4 board 650 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

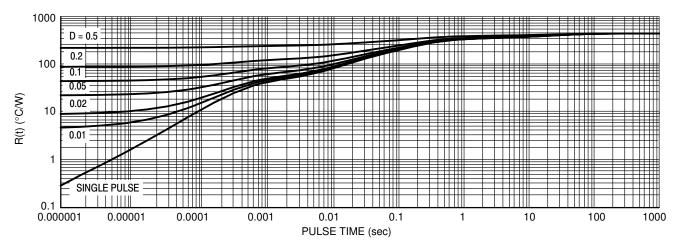


Figure 1. Thermal Response (Note 1)

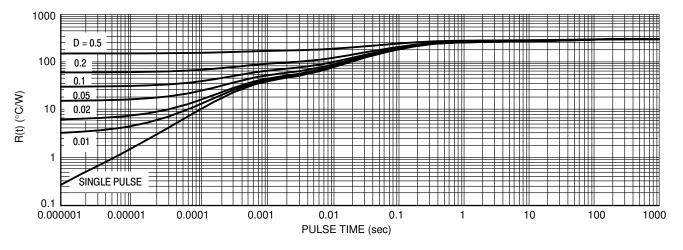
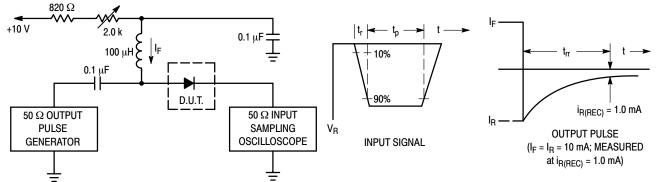


Figure 2. Thermal Response (Note 2)

$\textbf{ELECTRICAL CHARACTERISTICS} \ (T_A = 25^{\circ}C \ unless \ otherwise \ noted)$

| <i>'</i> | | | | | |
|--|------------------|-----|--------------------------|--------------------------|------|
| Characteristic | Symbol | Min | Тур | Max | Unit |
| Reverse Leakage $(V_R = 10 \text{ V})$ $(V_R = 30 \text{ V})$ | I _R | | 30 52 | 110 170 | μΑ |
| Forward Voltage $(I_F = 10 \text{ mA})$ $(I_F = 100 \text{ mA})$ $(I_F = 200 \text{ mA})$ $(I_F = 500 \text{ mA})$ | V _F | | 200 275 205 370 | 340 380 420 450 | mV |
| Total Capacitance (V _R = 1.0 V, f = 1.0 MHz) | C _T | | 85 | | pF |
| Reverse Recovery Time $(I_F = I_R = 10 \text{ mA}, I_{R(REC)} = 1.0 \text{ mA}, Figure 3)$ | t _{rr} | | 23 | | ns |
| Peak Forward Recovery Voltage (I _F = 100 mA, t _r = 20 ns, Figure 4) | V _{FRM} | | 395 | | mV |



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.

- 2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.
- $3. t_n * t_m$

Figure 3. Recovery Time Equivalent Test Circuit

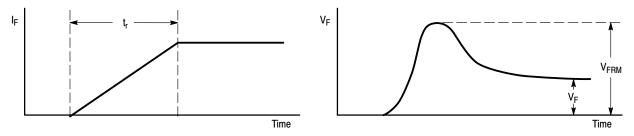


Figure 4. Peak Forward Recovery Voltage Definition

TYPICAL CHARACTERISTICS

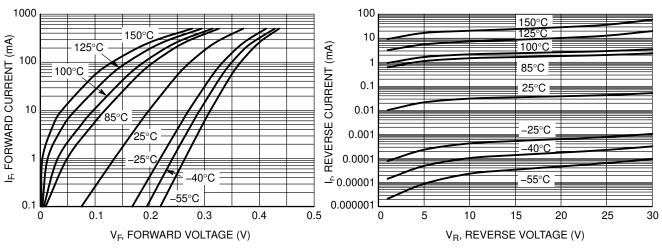


Figure 5. Forward Voltage

Figure 6. Leakage Current

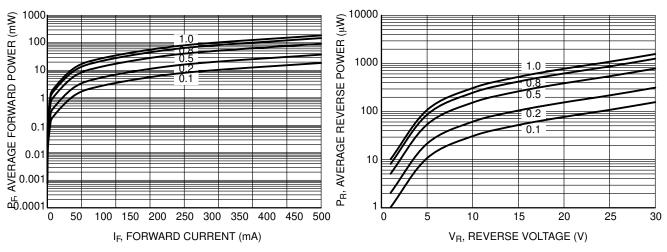


Figure 7. Average Forward Power Dissipation

Figure 8. Average Reverse Power Dissipation

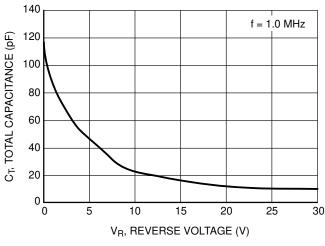


Figure 9. Total Capacitance

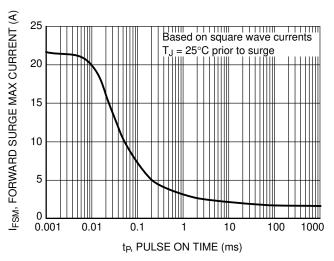
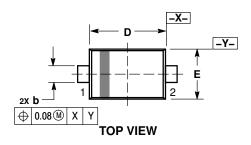
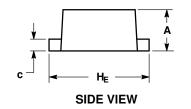


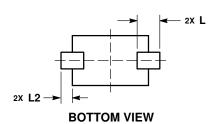
Figure 10. Forward Surge Current

PACKAGE DIMENSIONS

SOD-523 **CASE 502** ISSUE E







NOTES:

- NOTES.

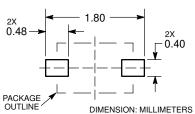
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PRO-
- TRUSIONS, OR GATE BURRS

| | MILLIMETERS | | | |
|-----|-------------|------|------|--|
| DIM | MIN | NOM | MAX | |
| Α | 0.50 | 0.60 | 0.70 | |
| b | 0.25 | 0.30 | 0.35 | |
| С | 0.07 | 0.14 | 0.20 | |
| D | 1.10 | 1.20 | 1.30 | |
| E | 0.70 | 0.80 | 0.90 | |
| HE | 1.50 | 1.60 | 1.70 | |
| L | 0.30 REF | | | |
| L2 | 0.15 | 0.20 | 0.25 | |

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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